

FACED PANEL

ARES UB55

SUPPORT: Chipboard, MDF
FORMAT: 5600 x 2070 mm
THICKNESS: from 8 to 38 mm
TEXTURE ORIENTATION: All over
BACK TEXTURE: Ares
NOMINAL OVERTHICKNESS: +0.3 mm

LAMINATE

ARES UB55

TYPE: HPL
FORMAT: 2760 x 2040 mm
THICKNESS: 0.9 mm

EDGE

ARES UB55

TYPE: ABS
HEIGHT: from 15 to 330 mm
THICKNESS: from 0.5 to 2.0 mm

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